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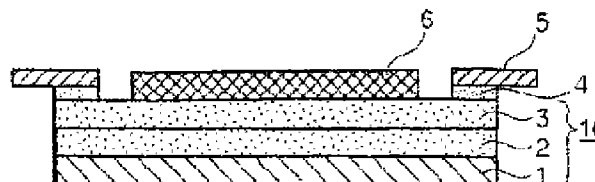
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TITLE : WAFER DICING/BONDING SHEET,
AND MANUFACTURING METHOD OF
SEMICONDUCTOR DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a wafer dicing/bonding sheet for transferring an adhesive layer where a die bond layer of excellent storage modulus is formed for smooth pasting to a semiconductor wafer and pick-up operation of an IC chip onto the rear surface of the IC chip.

SOLUTION: The wafer dicing/bonding sheet has a first and second adhesive layers 2 and 3 laminated sequentially on a base material 1. The minimum value of storage modulus of the second adhesive layer 3 is 10^8 pa or higher at -50 to 150°C after curing.

The method for manufacturing a semiconductor device includes the following processes. A semiconductor wafer is pasted to the second adhesive layer 3 of the wafer dicing/bonding sheet. The semiconductor wafer is diced to provide an IC chip. The second adhesive layer 3 and the first adhesive layer 2 are tightly fitted and left on the rear surface of the IC chip, and peeled from the base material. The IC chip is press-fitted under heat on a die pad through the first adhesive layer.

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